

What is claimed is:

1. A method for manufacturing a semiconductor integrated circuit card comprising the steps of:

forming a circuit pattern on a substrate;

bonding a plurality of semiconductor integrated circuit chips onto a first surface of said substrate having the circuit pattern formed thereon, and also connecting electrodes of said semiconductor integrated circuit chips to said circuit pattern;

applying a first seal resin onto each of said semiconductor integrated circuit chips;

disposing a first reinforcement metal plate above said first seal resin;

pressurizing said first seal resin via said first reinforcement metal plate so as to let flow said first seal resin along a peripheral face of said semiconductor integrated circuit chips;

hardening said seal resin flown along the peripheral face of said semiconductor integrated circuit chips; and

thereafter dividing a product into a semiconductor integrated circuit chip at every circuit pattern.

2. A method for manufacturing a semiconductor integrated circuit card according to claim 1 further comprising the steps of:

applying a second seal resin onto a second reinforcement

metal plate;

disposing said second reinforcement metal plate on a second surface of said substrate; and

pressuring said first and second seal resins via said first and second reinforcement metal plates such that said first and second seal resins flow along the peripheral face of said semiconductor integrated circuit chips.

3. A method for manufacturing a semiconductor integrated circuit card according to claim 1 further comprising the step of:

disposing an individually divided semiconductor circuit chip on a roll film and coating the same.

4. A method for manufacturing a semiconductor integrated circuit card according to claim 3 further comprising the step of:

heating said thin film roll on which said semiconductor integrated circuit chip coated with the thin film.

5. A method for manufacturing a semiconductor integrated circuit card according to claim 4 further comprising the step of:

thereafter manufacturing a card connected plate in which a plurality of semiconductor integrated circuit cards are connected in line: and

dividing said card connected plate into an individual semiconductor integrated circuit card.

6. A semiconductor integrated circuit card comprising:  
a substrate having a circuit pattern formed thereon;  
a semiconductor integrated circuit chip bonded onto said substrate and having an electrode connected to said circuit pattern;

a first reinforcement metal plate disposed on a surface of said semiconductor integrated circuit chip;

a first seal resin portion disposed on a peripheral face of said semiconductor integrated circuit chip and sticking said first reinforcement metal plate; and

a resin layer covering said semiconductor integrated circuit chip.

7. A semiconductor integrated circuit card according to claim 6, comprising:

a second reinforcement metal plate disposed on a surface of said substrate opposite a surface at which said semiconductor integrated circuit chip is connected to the circuit pattern.

8. A semiconductor integrated circuit card according to claim 6, comprising:

a resin layer covering said semiconductor integrated circuit chip.

9. A semiconductor integrated circuit card according to claim 6, comprising:

an armoring resin layer formed on both faces of said substrate having said sealed semiconductor integrated circuit

chip.

10. A semiconductor integrated circuit card as claimed in claim 7, wherein said second reinforcement metal plate is bonded onto said substrate via said second seal resin.

11. A semiconductor integrated circuit card as claimed in claim 6, wherein said substrate is a film substrate.

12. A semiconductor integrated circuit card as claimed in claim 6, wherein said first reinforcement metal plate has a surface which is similar to and larger in area than a top surface of said semiconductor integrated circuit chip.

13. A semiconductor integrated circuit card as claimed in claim 7, wherein an armoring resin layer is formed on each of both faces of said substrate having said sealed semiconductor integrated circuit chip.

14. A semiconductor integrated circuit card as claimed in claim 7, wherein said substrate is a film substrate.

15. A semiconductor integrated circuit card as claimed in claim 7, wherein said second reinforcement metal plate has a surface which is similar to and larger in area than a lower face of said semiconductor integrated circuit chip.